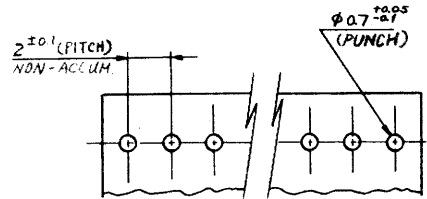
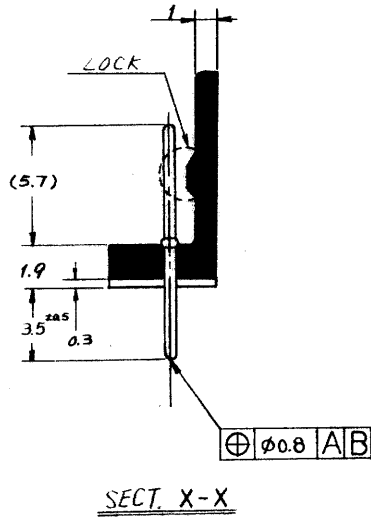
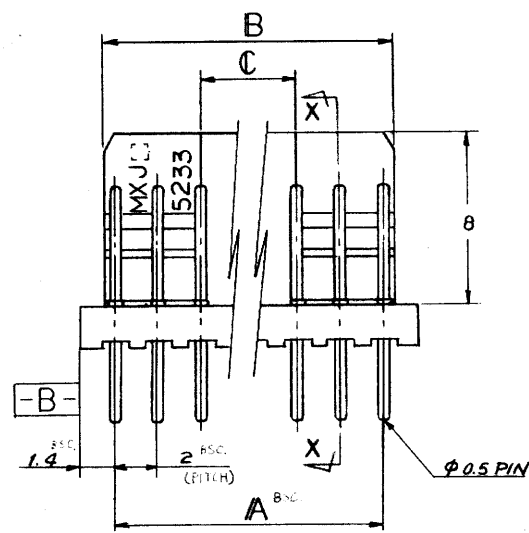
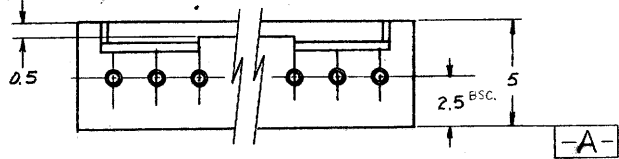


EDP NO. 10-32-1* *3 SD -5233-NA
 ENG. NO.

単位: MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING



RECOMMENDED P/C BOARD HOLE DIMENSIONS.

NOTE :

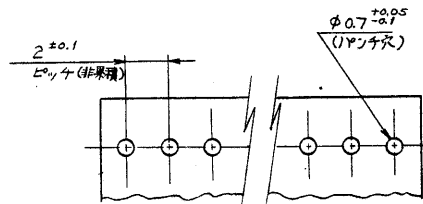
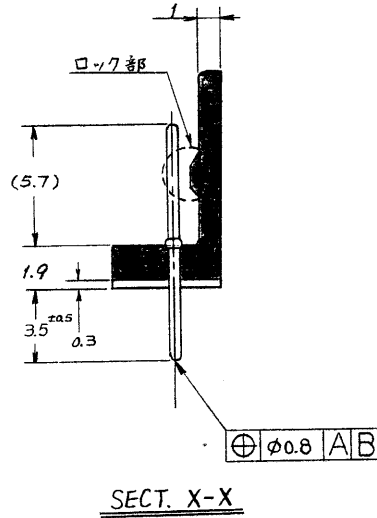
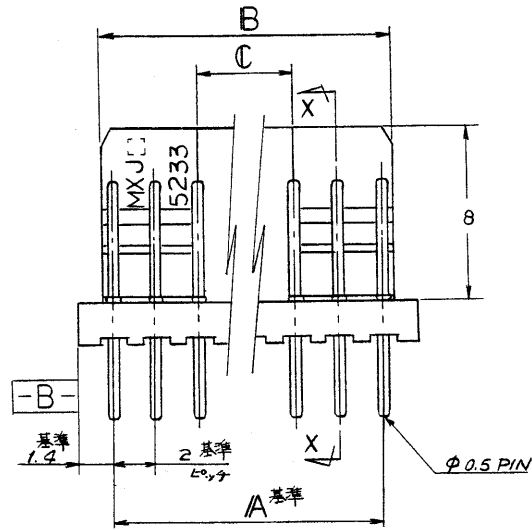
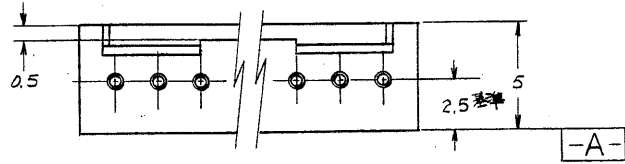
1. THESE WAFER ASSEMBLIES 5233-NA SHOULD BE MATED WITH MICRO SPOX HOUSINGS 5231-N.
2. DIM C SHOULD BE APPLIED TO THE WAFER ASSEMBLIES THE NO. OF CIRCUITS OF WHICH IS MORE THAN 6.
3. MORE THAN 8 CIRCUITS, NO LOCK IS PROVIDED.

	A	B	C	EDP NO.	ENG. NO.	NO. OF CTS.
38	39.2	30	10-32-1203	5233-20A	20	
36	37.2	28	-1193	-19A	19	
34	35.2	26	-1183	-18A	18	
32	33.2	24	-1173	-17A	17	
30	31.2	22	-1163	-16A	16	
28	29.2	20	-1153	-15A	15	
26	27.2	18	-1143	-14A	14	
24	25.2	16	-1133	-13A	13	
22	23.2	14	-1123	-12A	12	
20	21.2	12	-1113	-11A	11	
18	19.2	10	-1103	-10A	10	
16	17.2	8	-1093	-09A	9	
14	15.2	6	-1083	-08A	8	
12	13.2	4	-1073	-07A	7	
10	11.2	2	-1063	-06A	6	
8	9.2	-	-1053	-05A	5	
6	7.2	-	-1043	-04A	4	
4	5.2	-	-1033	-03A	3	
2	3.2	-	10-32-1023	5233-02A	2	

材料 MATERIAL	WAFFER : NYLON 66, UL94V-0
PIN	: BRASS PIN OVER COPPER PLATING
仕上 FINISH	—
適用電線範囲 WIRE RANGE	—
装填外径 INS. RANGE	—
DRAWN BY	CHK'D BY
APP'D BY	尺 度 SCALE 4-1
DATE	SCALE 4-1

角度 ANGLE	± 3'	C	REVISED ECN	DR	DATE
30 以上 OVER	±0.3	B	2267	10/6/81	
10 以上 30 未満 UNDER	±0.25	A	1657	5/1/80	
10 未満 UNDER	±0.2	0	1522	1/6/80	

MOLEX-JAPAN CO., LTD.
 日本モレックス株式会社
 EDP NO. 10-32-1* *3
 ENG. NO. SD -5233-NA
 TITLE 名称: MICRO SPOX WAFER ASSEMBLY



基板穴推定寸法

注)

1. 嵌合相手: 5231-N
2. C寸法は6極以上に適用.
3. 8極以上はロックなし.

28	27.2	20	10-32-1153	5233-15A	15
26	27.2	18	-1143	-14A	14
24	25.2	16	-1133	-13A	13
22	23.2	14	-1123	-12A	12
20	21.2	12	-1113	-11A	11
18	19.2	10	-1103	-10A	10
16	17.2	8	-1093	-09A	9
14	15.2	6	-1083	-08A	8
12	13.2	4	-1073	-07A	7
10	11.2	2	-1063	-06A	6
8	9.2	-	-1053	-05A	5
6	7.2	-	-1043	-04A	4
4	5.2	-	10-32-1033	5233-03A	3
A	B	C	EDP NO.	ENG. NO.	N極数

E	変更 (JC60342)	SM	9/6/9
D	変更 (J90332)	TK	8/9/6
C	変更 ECN 2267	JK	10/5/8
B	変更 ECN 1657	JK	5/4/8
A	X'削除 ECN 1522	JK	1/6/8
O	作成	JK	9/2/4
記号	変更内容	DR.	日付
LTR	REVISION RECORD	CHK	DATE

角度 ANGLE	± 3°
30 以上 OVER	± 0.3
10 以上 OVER 30 UNDER	± 0.25
10 未満 UNDER	± 0.2
一般公差	
GENERAL TOLERANCES	

材料 MATERIAL	材料名: 667ロソ, UL94V-0
仕上 FINISH	ピン: 黄銅面, 鍍下地スズメッキ
適用電線範囲 WIRE RANGE	---
被覆外径 INS. RANGE	---
DRAWN BY	CHK'D BY
APP'D BY	尺 度 SCALE 4-1

MOLEX-JAPAN CO., LTD. 日本モレックス株式会社	
EDP NO.	10-32-1* *3
ENG. NO.	SD-5233-NA
TITLE 名称:	MICRO SPOX WAFER ASSEMBLY